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(54) Title: ELECTRONIC DEVICE

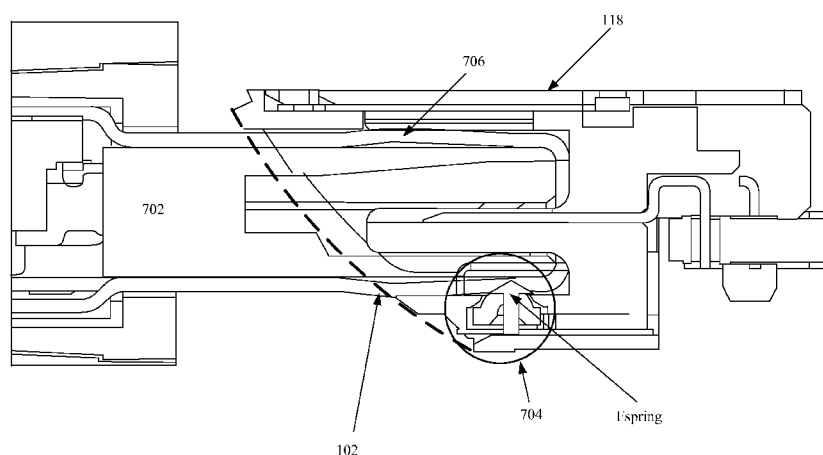


Fig. 7

(57) Abstract: Heat sealing a connector assembly can be performed by providing connector assembly in component accessible state, overlaying sealing tape on electrical contacts and housing, sealing tape being impregnated with heat sensitive adhesive, the overlaying leaving the dimples exposed, and sealing the connector assembly by applying heat to heat sensitive sealing tape.



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